# Space Flight Surface Mount Flat Packs Resistor Networks



#### 8900 Space Series

- 100% screened to NASA EEE-INST-002 Level 1
- Gold to gold bonded lead construction no internal solder connections or wire bonds
- Excellent passive solution for space flight hardware
- Self Passivating TaNFilm® element with superior moisture performance

The 8900 Space Series features our TaNFilm<sup>®</sup> Flat Pack Network superior moisture performance of tantalum nitride resistor film system. Rugged, welded lead construction eliminates fragile wire bond construction and provides superior surface mount reliability. These parts are screened per MIL-PRF-83401 then upgraded to the stringent screening requirements for NASA space flight requirements.

#### **Electrical Data**

		Available Absolute Tolerances	Available Ratio Tolerance (reference R1)	Available Absolute TCR (ppm/°C)	Tracking TCR (reference to R1) (ppm/°C)	MIL-PRF-83401 Ratings	
Package	Range					Voltage (not to exceed √P x R)	Element Power Rating 70°C
Isolated Schematic	20Ω - 99Ω	FGJ	FGJ	±100	±10	501/	50mW
	100Ω - 121KΩ	BFGJ	ABFG	±25, ±50, ±100	±5	507	
Bussed Schematic	20Ω - 499Ω	FGJ	FGJ	±100	±20	50)/	25mW
	500.0Ω - 100ΚΩ	BFGJ	ABFG	±25, ±50, ±100	±5	507	

#### Screening Data

Sorios	Optional Precap Precap		Screening	Addition Screening IAW EEE-INST-002 Level 1					
Туре	per MIL-STD-883	Source Verification	per MIL-PRF-83401	Serialized	Thermal Shock 25 Cycles	Power Conditioning 100 Hours	Optional Final Source Inspection	Marking P/N	
89xxSQ	Yes	Yes	Yes	Yes	Yes	Yes	Yes	89xxSQ -xx-yyyyzz	

General Note IRC reserves the right to make changes in product specification without notice or liability. All information is subject to IRC's own data and is considered accurate at time of going to print.



# Space Flight Surface Mount Flat Packs Resistor Networks



### **Environmental Data**

Environnmental Test	Maximum ∆R per	Performance		
MIL-PRF-83401	Characteristic H	Typical	Maximum	
Thermal Shock and Power Conditioning	±0.50%	±0.02%	±0.10%	
Low Temperature Operation	±0.10%	±0.01%	±0.01%	
Short Time Overload	±0.10%	±0.01%	±0.05%	
High Temperature Exposure	±0.20%	±0.03%	±0.10%	
Effects of Solder	±0.10%	±0.02%	±0.10%	
Moisture Resistance	±0.40%	±0.03%	±0.10%	
Life	±0.50%	±0.03%	±0.10%	

### Physical and Schematic Data



# Space Flight Surface Mount Flat Packs Resistor Networks



### **Power Derating Curve**



### Ordering Data

Prefix · · · · · · · FP - 8989 SQ - 05 - 1001 - B B - 1
Model
8987 = 14-pin bussed schematic B
8989 = 14-pin isolated schematic A
8998 = 16-pin bussed schematic B
8999 = 16-pin isolated schematic A
SQ = EEE-INST-002 Level 1
TCR Code
04 = ±300ppm/°C; 05 = ±100ppm/°C; 06 = ±50ppm/°C 07 = ±25ppm/°C
<b>Resistance Code</b> 4-Digit resistance code. Ex: $1002 = 10K\Omega$ ; $50R0 = 50\Omega$
<b>Absolute Tolerance Code</b> J = ±5%; G = ±2%; F = ±1%; B = ±0.1%
<b>Optional R1 Ratio Tolerance Code</b> G = ±2%; F = ±1%; D = ±0.5%; B = ±0.1%; A = ±0.05%
Terminal Finish Option .   0 = gold plating; 1 = 60/40 Sn/Pb hot solder dip .

For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.